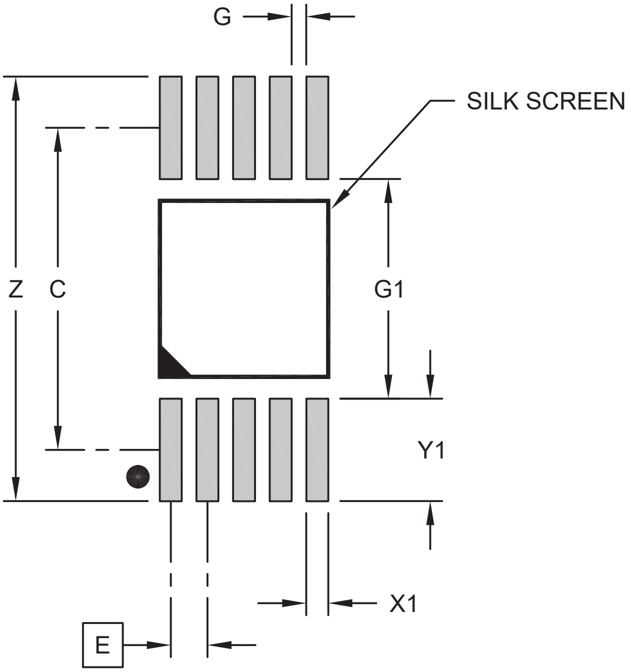
10-Lead Plastic Micro Small Outline Package (DQA)- 3x3x1.0 mm Body [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C		4.40	
Overall Width	Z			6.06
Contact Pad Width (X10)	X1	0.28	0.30	0.32
Contact Pad Length (X10)	Y1	1.24	1.26	1.28
Distance Between Pads (X5)	G1	3.00		
Distance Between Pads (X8)	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.